

P-Channel Enhancement-Mode Vertical DMOS FETs

Ordering Information

BV _{DSS} /	R _{DS(ON)} I _{D(O}	I _{D(ON)}	Ord	rder Number / Package			
BV _{DGS}	(max)	(min)	TO-92	TO-92 TO-236AB*			
-60V	12Ω	-0.5A	VP2106N3	_	_		
-100V	12Ω	-0.5A	_	VP2110K1	VP2110ND		

Product marking for SOT-23:

P1A*

where * = 2-week alpha date code

Features

- □ Free from secondary breakdown
- Low power drive requirement
- Ease of paralleling
- Low C_{iss} and fast switching speeds
- Excellent thermal stability
- Integral Source-Drain diode
- High input impedance and high gain
- Complementary N- and P-channel devices

Applications

- Motor controls
- Converters
- Amplifiers
- Switches
- Power supply circuits
- Drivers (relays, hammers, solenoids, lamps, memories, displays, bipolar transistors, etc.)

Absolute Maximum Ratings

Drain-to-Source Voltage	BV_{DSS}
Drain-to-Gate Voltage	BV _{DGS}
Gate-to-Source Voltage	± 20V
Operating and Storage Temperature	-55°C to +150°C
Soldering Temperature*	300°C

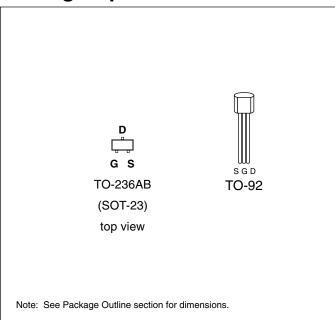
^{*} Distance of 1.6 mm from case for 10 seconds.

Advanced DMOS Technology

These enhancement-mode (normally-off) transistors utilize a vertical DMOS structure and Supertex's well-proven silicon-gate manufacturing process. This combination produces devices with the power handling capabilities of bipolar transistors and with the high input impedance and positive temperature coefficient inherent in MOS devices. Characteristic of all MOS structures, these devices are free from thermal runaway and thermally-induced secondary breakdown.

Supertex's vertical DMOS FETs are ideally suited to a wide range of switching and amplifying applications where high breakdown voltage, high input impedance, low input capacitance, and fast switching speeds are desired.

Package Options



11/12/01

[†]MIL visual screening available.

^{*}Same as SOT-23. All units shipped on 3,000 piece carrier tape reels.

Thermal Characteristics

Package	I _D (continuous)*	I _D (pulsed)	Power Dissipation @ T _A = 25°C	$^{ heta_{ extsf{jc}}}$ $^{\circ}$ C/W	θ _{ja} °C/W	I _{DR} *	I _{DRM}
TO-236AB	-120mA	-400mA	0.36W	200	350	-120mA	-400mA
TO-92	-0.25A	-0.8A	0.74W	125	170	-0.25A	-0.8A

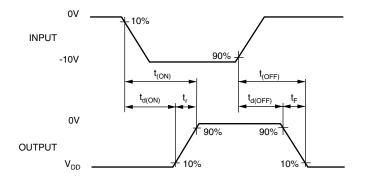
 $^{^{\}star}$ I_{D} (continuous) is limited by max rated $T_{j\cdot}$

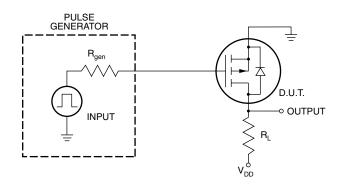
Electrical Characteristics (@ 25°C unless otherwise specified)

Symbol	Parameter		Min	Тур	Max	Unit	Conditions	
BV _{DSS}	Drain-to-Source	VP2110	-100			.,	I _D = -1.0mA, V _{GS} = 0V	
	Breakdown Voltage	VP2106	-60			V		
V _{GS(th)}	Gate Threshold Voltage		-1.5		-3.5	V	$V_{GS} = V_{DS}$, $I_D = -1.0$ mA	
$\Delta V_{GS(th)}$	Change in V _{GS(th)} with Temperature			5.8	6.5	mV/°C	$I_D = -1.0 \text{mA}, V_{GS} = V_{DS}$	
I _{GSS}	Gate Body Leakage			-1.0	-100	nA	$V_{GS} = \pm 20V$, $V_{DS} = 0V$	
I _{DSS}	Zero Gate Voltage Drain Current				-10	μΑ	$V_{GS} = 0V$, $V_{DS} = Max$ Rating	
					-1	mA	$V_{GS} = 0V$, $V_{DS} = 0.8$ Max Rating $T_A = 125$ °C	
I _{D(ON)}	ON-State Drain Current		-0.50	-1.0		Α	$V_{GS} = -10V, V_{DS} = -25V$	
R _{DS(ON)}				11	15	Ω	$V_{GS} = -5V, I_{D} = -0.1A$	
				9.0	12		$V_{GS} = -10V, I_D = -0.5A$	
$\Delta R_{DS(ON)}$	Change in R _{DS(ON)} with Temperature			0.55	1.0	%/°C	$V_{GS} = -10V, I_D = -0.5A$	
G_{FS}	Forward Transconductance		150	200		mΩ	$V_{DS} = -25V, I_{D} = -0.5A$	
C _{ISS}	Input Capacitance			45	60			
Coss	Common Source Output Capacitance			22	30	pF	$V_{GS} = 0V$, $V_{DS} = -25V$ f = 1 MHz	
C _{RSS}	Reverse Transfer Capacitance			3	8		1 = 1 (VII 12	
$t_{d(ON)}$	Turn-ON Delay Time			4	5			
t _r	Rise Time			5	8	ns	$V_{DD} = -25V$ $I_{D} = -0.5A$	
t _{d(OFF)}	Turn-OFF Delay Time			5	9		$R_{GEN} = 25\Omega$	
t _f	Fall Time			4	8			
V_{SD}	Diode Forward Voltage Drop			-1.2	-2.0	V	$I_{SD} = -0.5A, V_{GS} = 0V$	
t _{rr}	Reverse Recovery Time			400		ns	$I_{SD} = -0.5A, V_{GS} = 0V$	

Notes:

Switching Waveforms and Test Circuit

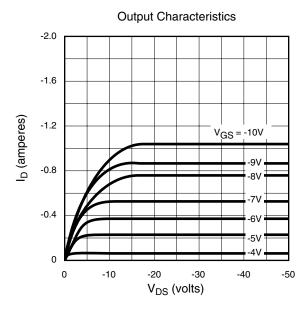


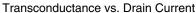


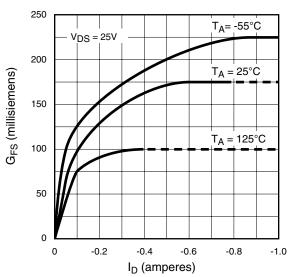
^{1.}All D.C. parameters 100% tested at 25°C unless otherwise stated. (Pulse test: 300 µs pulse, 2% duty cycle.)

^{2.}All A.C. parameters sample tested.

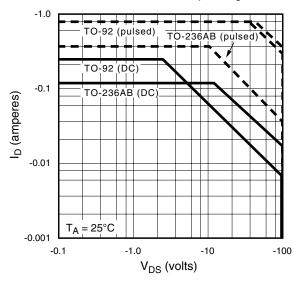
Typical Performance Curves



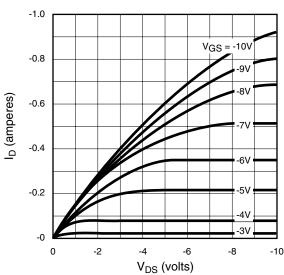




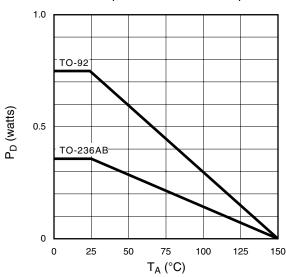
Maximum Rated Safe Operating Area



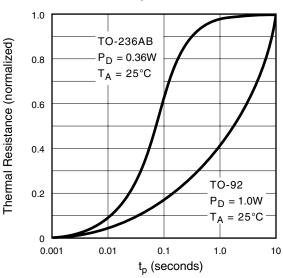
Saturation Characteristics



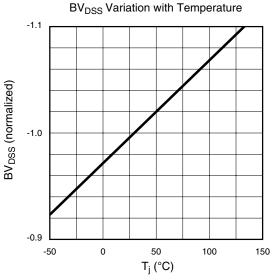
Power Dissipation vs. Ambient Temperature



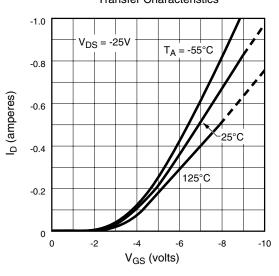
Thermal Response Characteristics



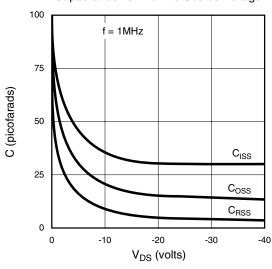
Typical Performance Curves



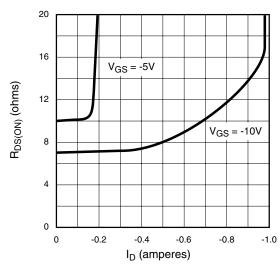




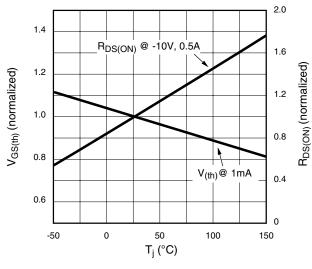
Capacitance vs. Drain-to-Source Voltage



On-Resistance vs. Drain Current



 $V_{(th)}$ and R_{DS} Variation with Temperature



Gate Drive Dynamic Characteristics

